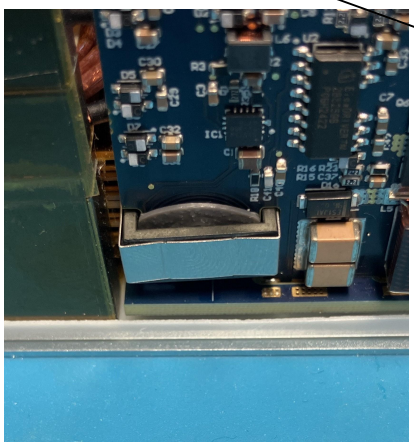
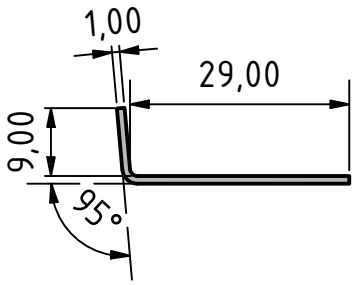
BILL OF MATERIALS			
COMPONENT	QUANTITY	DESCRIPTION	MPN
1	1	Tin-plated copper heatsink	HT100001621
2	1	Self-adhesive thermal interface material	TF100001621
3	1	Power card	PW100001622
4	1	FR4 spacer	SP100001621
5	2	Ferrite core halves	B65513J0000R049/ EPCOS-TDK

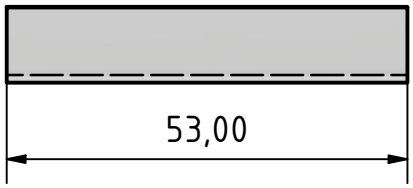


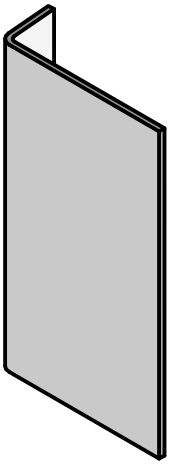
Secure ferrite cores with B65514A2000X000 clip (not pictured).

					Datum	Name
				Gezeich	02.04.2026	Wernegger
				Kontroll		
				Norm		
				PW100001622		1
						A4
Status	Änderungen	Datum	Name			

PARTS LIST		
OBJEKT	ANZAHL	BAUTEILNUMMER
1	1	HT100001621







					Datum	Name
				Gezeich	02.04.2026	Wernegger
				Kontroll		
				Norm		

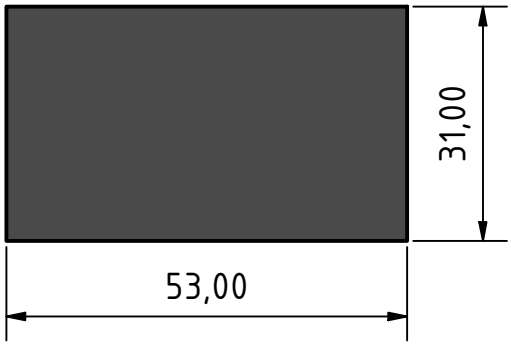
PW100001622

2

A4

Status	Änderungen	Datum	Name

Material: Bergquist BOND PLY TBP 1400LMS-HD
Legacy desc.: BMPLMS-HD0.010-00-XXXX
(last four digits refer to patch size, e.g. 1212 = 12x12 inch)



					Datum	Name
				Gezeich	02.04.2026	Wernegger
				Kontroll		
				Norm		

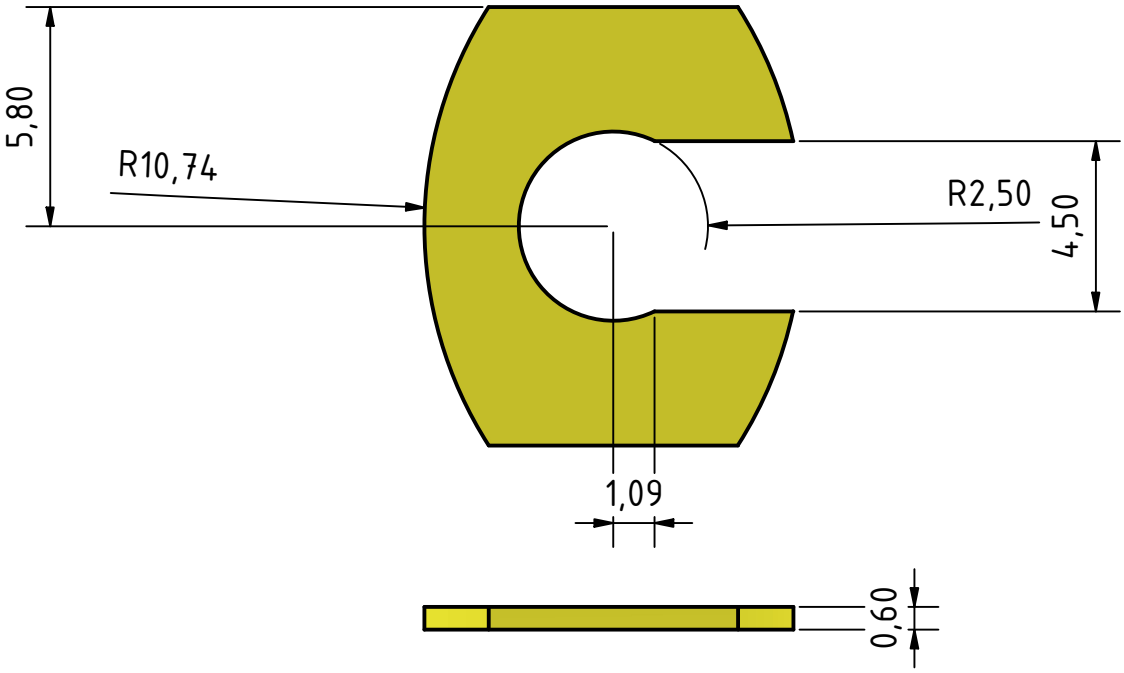
TF100001621

PW100001622

3

A4

Status	Änderungen	Datum	Name



		Material: FR4	
	Datum	Name	
Gezeich	02.04.2026	Wernegger	SP100001621
Kontroll			
Norm			
		PW100001622	4
			A4

Status	Änderungen	Datum	Name